

MRSI-LEAP

ULTRA HIGH SPEED DIE BONDER



- Very high throughput
- Exceptionally stable, $\pm 1\mu\text{m}$ @ 3σ placement accuracy
- Supports multiple wafers and multiple automated tool changes

MRSI, Mycronic has been serving optoelectronic customers for the past 40+ years and understands their requirement to scale efficiently in today's fast-paced marketplace.

Applications & Features

- The MRSI-LEAP is designed for high-volume manufacturing applications of optical modules, including Chip-on-Carrier (CoC), Chip-on-Submount (CoS), and Chip-on-Baseplate (CoB) assemblies utilizing epoxy stamping die bonding
- Placement accuracy is $\pm 1\mu\text{m}$ @ 3σ with pick & place throughput exceeding 1,000 UPH
- Material input methods include wafer, Waffle pack, Gel-Pak®, and customized fixtures
- Built-in conveyor designed for single fixture or multiple cassette inputs to transport large carriers of substrates for Active Optical Cables (AOC) or similar chip-on-printed circuit board (PCB) applications, gold-box packaging, and CoC assemblies in fixtures
- Flip-chip bonding, UV epoxy dispensing, in-situ UV curing, wafer-level packaging, and other processes are available

Configuration Highlights

- Advanced machine vision and tool design
- Modular design and field upgradeable
- Supports two 8-inch wafers and two 6-inch wafers
- Built-in conveyor and magazine design for high efficiency and throughput
- Automated dispensing and UV cure options available

Value to our Customers

- Industry-leading throughput and ultra-high accuracy in high-volume manufacturing with a pick-and-place process capable of achieving over 1,000 units per hour (UPH)
- The machine achieves an accuracy of less $\pm 1\mu\text{m}$ at 3σ , ensuring long-term stability
- Easy to use icon-based interface running on a Windows™ platform for ease of programming, and low-cost machine maintenance
- Industry-leading local technical support teams and application expertise
- 40+ years of experience in the industry with reliable 24/7 field operations



North America

554 Clark Rd., Tewksbury, MA
USA 01876
Tel: +1 978 667 9449
sales.mrsi@mycronic.com
[https://www.mycronic.com/
product-areas/die-bonding/](https://www.mycronic.com/product-areas/die-bonding/)

MRSI China

101, Block A, Huahan
Innovation Park,
Langshan Road, Shenzhen,
China 518057
Tel: +86 755 26414155

MRSI EMEA

(Distributor and Demo Center)
Distek Strumenti & Misure Srl
Via Generale Giordano Orsini 42
80123 Napoli, Italy
marco@distek.it
Tel: +39 348 3837817